

SM72240 SolarMagic 5-Pin Microprocessor Reset Circuit

Check for Samples: SM72240

FEATURES

- Renewable Energy Grade
- Precise monitoring of 5V supply voltages
- Fully specified over temperature
 - -40°C to +125°C
- 100 ms minimum Power-On Reset pulse width, 190 ms typical:
 - Active-Low RESET Open Drain Output
- Guaranteed RESET Output valid for V_{CC} ≥ 1V
- Low Supply Current, 6µA typical
- Power supply transient immunity
- Compatible with MAX811/812 applications

APPLICATIONS

- **Microprocessor Systems**
- **Computers**
- **Controllers**
- **Intelligent Instruments**
- Portable/Battery-Powered Equipment

DESCRIPTION

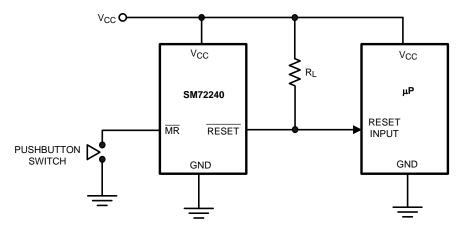
The SM72240 microprocessor supervisory circuit monitors the power supplies in microprocessor and digital systems. It provides a reset to the microprocessor during power-up, power-down, brown-out conditions, and manual reset.

The SM72240 asserts a reset signal whenever the supply decreases below the factory-programmed reset threshold. Reset will be asserted for at least 100ms even after V_{CC} rises above the reset threshold.

The SM72240 has an active-low open-drain RESET output.

The SM72240 is suitable for monitoring 5V. With a low supply current of only 6µA, the SM72240 is ideal for use in portable equipment. The SM72240 is available in the 5-pin SOT-23 package.

Typical Application Circuit



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Connection Diagram

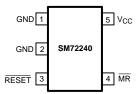


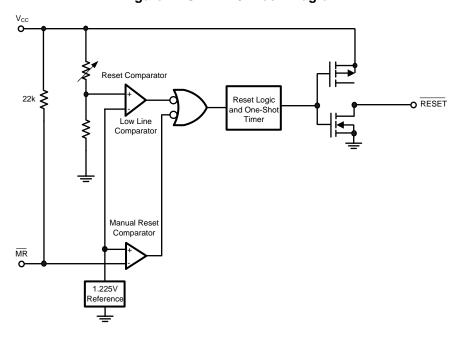
Figure 1. 5-Pin SOT-23 Package See Package Number DBV

PIN DESCRIPTIONS

Pin	Name	Function
1	GND	Ground reference
2	GND	Ground reference, device substrate, connect to ground.
3	RESET	Active-low output. $\overline{\text{RESET}}$ remains low while V_{CC} is below the reset threshold voltage, and for 190 ms after V_{CC} rises above the reset threshold voltage.
4	MR	Active-low input. Reset is asserted whenever this pin is pulled low and remains asserted for 190 ms after the $\overline{\text{MR}}$ pin goes high. May be left open.
5	V _{cc}	Supply Voltage (+5V, nominal)

Block Diagram

Figure 2. SM72240 Block Diagram





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Submit Documentation Feedback

Product Folder Links: SM72240



Absolute Maximum Ratings (1)(2)

	-0.3V to 6.0V				
RESET, RESET					
Input Current, V _{CC} Pin					
Output Current, RESET, RESET Pin					
ESD Rating ⁽³⁾					
SOT-23 ⁽⁴⁾	320mW				
•	-40°C to +125°C				
Maximum Junction Temperature					
Storage Temperature Range					
	+300°C				
	SOT-23 ⁽⁴⁾				

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which the device operates correctly. Operating ratings do not imply guaranteed performance limits. For guaranteed performance limits and associated test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) The human body model is a 100pF capacitor discharged through a 1.5k Ω resistor into each pin.
- (4) At elevated temperatures, devices must be derated based on package thermal resistance. The device must be derated at 4.5mW/°C at ambient temperatures above 70°C. The device has internal thermal protection.

Electrical Characteristics

Typical values are at T_A = +25°C. Limits with standard typeface are for T_A = +25°C, and limits in boldface type apply for the operating temperature range -40°C to +125°C, unless otherwise noted. (1)

Symbol	Parameter	Co	Conditions		Тур	Max	Units
V_{CC}	V _{CC} Range			1.0		5.5	V
	Supply Current (I _{LOAD} = 0A)	SM72240-4.63	$V_{CC} = 5.5V$		8	15	
I _{CC}		SM72240-3.08	$V_{CC} = 3.6V$		7	10	μA
V_{TH}	Reset Threshold	SM72240-4.63	4.54 4.50	4.63	4.72 4.75	V	
		SM72240-3.08		3.03 3.00	3.08	3.14 3.15	V
V _{TH} Tempco	Reset Threshold Temperature Coefficient				30		ppm/°C
t _{RD}	V _{CC} to Reset Delay ⁽²⁾	$V_{CC} = V_{TH}$ to $(V_{TH} - 10)$	0mV)		20		μs
t _{RP}	Reset Active Timeout Period			100	190	560	ms
t _{MR}	MR Minimum Pulse Width			10			μs
t _{MD}	MR to Reset Propagation Delay				2		μs
	MR Glitch Immunity ⁽³⁾				100		ns
V_{IH}	MD lamest Three should			2.3			
V _{IL}	MR Input Threshold	$V_{CC} > V_{TH(MAX)}$			0.8	V	
	MR Pull-Up Resistance				22		kΩ
	RESETOutput Voltage Low	$V_{CC} = V_{TH} \text{ min, } I_{SINK} = 3$	3.2 mA		0.4	0.4	V
V_{OL}					0.3	V	
I _{IN}	RESET Output Leakage Current (SM72240)	V _{CC} > V _{TH} , RESET = 5.				0.5	μΑ

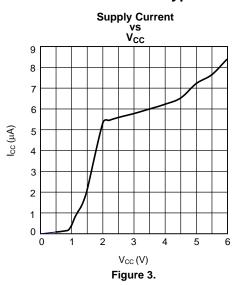
Production testing done at T_A = +25°C. Limits over the operating temperature range are guaranteed through correlation using Statistical <u>Quality</u> Control (SQC) methods.

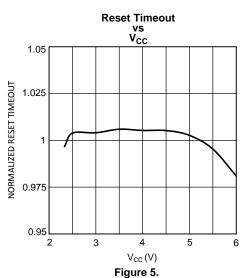
⁽²⁾ RESET Output.

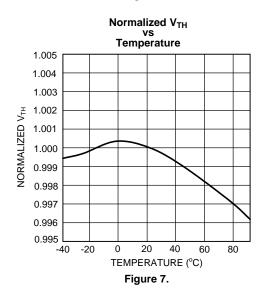
⁽³⁾ Glitches of 100 ns or less typically will not generate a reset pulse.

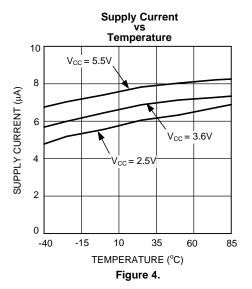


Typical Performance Characteristics









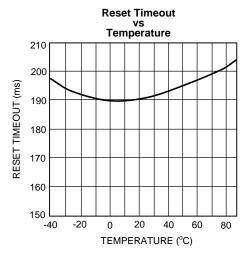
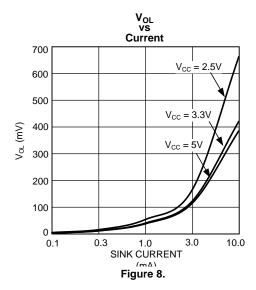
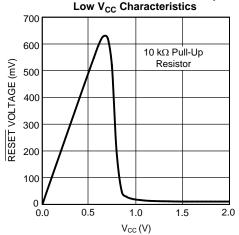


Figure 6.



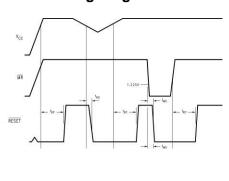


Typical Performance Characteristics (continued)



Timing Diagram

Figure 9.



CIRCUIT INFORMATION

RESET OUTPUT

The reset input of a μP initializes the device into a known state. The SM72240 microprocessor voltage monitoring circuit asserts a forced reset output to prevent code execution errors during power-up, power-down, and brownout conditions.

 $\overline{\text{RESET}}$ is guaranteed valid for $V_{CC} \ge 1V$. Once V_{CC} exceeds the reset threshold, an internal timer maintains the output for the reset timeout period. After this interval, reset goes high and the microprocessor initializes itself into a known state. $\overline{\text{RESET}}$ is active low.

As V_{CC} drops below the reset threshold (such as during a brownout), the reset activates (see the NEGATIVE-GOING V_{CC} TRANSIENTS section). When V_{CC} again rises above the reset threshold, the internal timer starts. Reset holds until V_{CC} exceeds the reset threshold for longer than the reset timeout period. After this time, reset releases.

Additionally, the Manual Reset input (MR) will initiate a forced reset. See the MANUAL RESET INPUT (MR) section

The SM72240 reset output ignores short duration glitches on V_{CC} and \overline{MR} . See the Applications Information section for details.



RESET THRESHOLD

The SM72240 is available with a reset voltage of 4.63V or 3.08V which are suitable for monitoring 5.0V or 3.3V supplies respectively.

MANUAL RESET INPUT (MR)

Many μP -based products require a manual reset capability, allowing th<u>e</u> operator to initiate a reset. The \overline{MR} input is fully debounced and provides an internal 22 k Ω pull-up. When the \overline{MR} input is pulled below V_{IL} (0.25 V_{CC}) for more than 100 ns, reset is asserted after a typical delay of 2 μ s. Reset remains active as long as \overline{MR} is held low, and releases after \overline{MR} rises above V_{IH} and the reset timeout period expires. Use \overline{MR} with digital logic to assert reset or to daisy chain supervisory circuits.

Applications Information

BENEFITS OF PRECISION RESET THRESHOLDS

A microprocessor supply supervisor must provide a reset output within a predictable range of the supply voltage. A common threshold range is between 5% and 10% below the nominal supply voltage. The SM72240 uses highly accurate circuitry to ensure that the reset threshold occurs only within this range (for 5.0V and 3.3V supplies). Table 1 shows how the standard reset threshold applies to 5.0V and 3.3V nominal supply voltages.

Table 1. Monitored Tolerance Table

Reset Threshold	Supply Voltage						
Reset Threshold	3.3V	5.0V					
4.63 ± %		90.8-94.4%					
3.08 ± %	91.8–95.2%						

ENSURING A VALID RESET OUTPUT DOWN TO $V_{CC} = 0V$

When V_{CC} falls below 1V, the <u>SM72240 RESET</u> output is unable to sink the rated current. A high-impedance CMOS logic input connected to RESET can therefore drift to undetermined voltages. To prevent this situation, a 100k Ω resistor should be connected from the RESET output to ground, as shown in Figure 10.

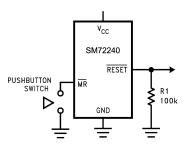


Figure 10. Circuit for \overline{RESET} Valid from $V_{CC} = 0V$

OPEN DRAIN OUTPUT

An open drain output allows easy paralleling of multiple microprocessor reset circuits without requiring additional logic gates. Open drain outputs also allow interfacing devices of differing logic levels or families, since the output pull-up resistor may be connected to any supply voltage up to 5.5V, regardless of V_{CC} .

The pull up resistor is calculated so that maximum current flow into $\overline{\text{RESET}}$ is less than 10 mA when activated. The resistor must be small enough so that the leakage current of all connected devices does not create an excessive voltage drop when the output is not activated. A resistor value of 100 k Ω will generally suffice.



NEGATIVE-GOING V_{CC} TRANSIENTS

The SM72240 is relatively immune to short negative-going transients or glitches on V_{CC} . Figure 11 shows the maximum pulse width a negative-going V_{CC} transient can have without causing a reset pulse. In general, as the magnitude of the transient increases, going further below the threshold, the maximum allowable pulse width decreases. Typically, a V_{CC} transient that goes 125 mV below the reset threshold and lasts 40 μ s or less will not cause a reset pulse. A 0.1 μ F bypass capacitor mounted as close as possible to the V_{CC} pin will provide additional transient rejection.

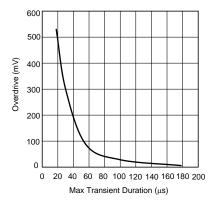


Figure 11. Maximum Transient Duration without Causing a Reset Pulse vs. Reset Comparator Overdrive





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
SM72240MF-3.08/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R133	Samples
SM72240MF-4.63/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2240	Samples
SM72240MFE-3.08/NOPB	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R133	Samples
SM72240MFE-4.63/NOPB	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2240	Samples
SM72240MFX-3.08/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	R133	Samples
SM72240MFX-4.63/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	2240	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.



PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SM72240MF-3.08/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SM72240MF-4.63/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SM72240MFE-3.08/NOPB	SOT-23	DBV	5	250	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SM72240MFE-4.63/NOPB	SOT-23	DBV	5	250	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SM72240MFX-3.08/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SM72240MFX-4.63/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

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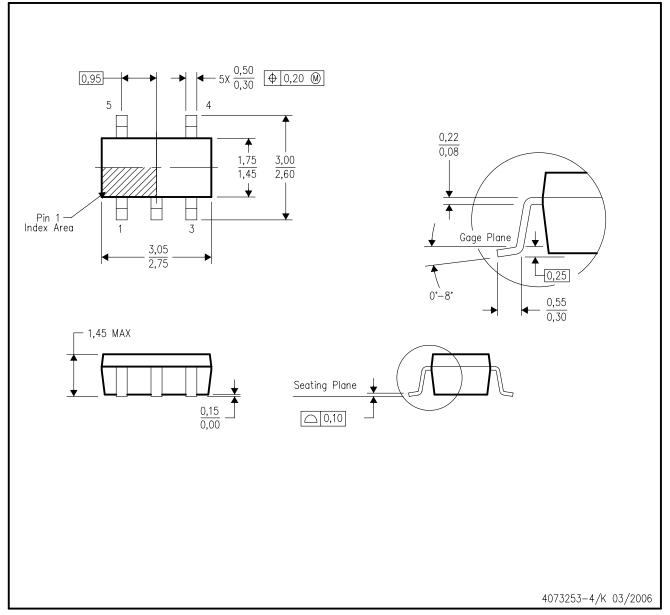


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SM72240MF-3.08/NOPB	SOT-23	DBV	5	1000	203.0	190.0	41.0
SM72240MF-4.63/NOPB	SOT-23	DBV	5	1000	203.0	190.0	41.0
SM72240MFE-3.08/NOPB	SOT-23	DBV	5	250	203.0	190.0	41.0
SM72240MFE-4.63/NOPB	SOT-23	DBV	5	250	203.0	190.0	41.0
SM72240MFX-3.08/NOPB	SOT-23	DBV	5	3000	206.0	191.0	90.0
SM72240MFX-4.63/NOPB	SOT-23	DBV	5	3000	206.0	191.0	90.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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